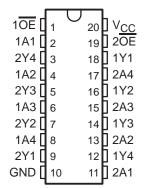
CD74FCT244, CD74FCT244AT BICMOS OCTAL BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS

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 BiCMOS Technology With Low Quiescent Power

- Buffered Inputs
- Noninverted Outputs
- Input/Output Isolation From V_{CC}
- Controlled Output Edge Rates
- 64-mA Output Sink Current
- Output Voltage Swing Limited to 3.7 V
- SCR Latch-Up-Resistant BiCMOS Process and Circuit Design
- Package Options Include Plastic Small-Outline (M) and Shrink Small-Outline (SM) Packages and Standard Plastic (E) DIP

CD74FCT244, CD74FCT244AT . . . E, M, OR SM PACKAGE (TOP VIEW)



description

The CD74FCT244 and CD74FCT244AT are octal buffer/line drivers with 3-state outputs using a small-geometry BiCMOS technology. The output stages are a combination of bipolar and CMOS transistors that limit the output high level to two diode drops below V_{CC} . This resultant lowering of output swing (0 V to 3.7 V) reduces the power-bus ringing [a source of electromagnetic interference (EMI)] and minimizes V_{CC} bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 64 mA.

These devices are organized as two 4-bit buffers/line drivers with separate active-low output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The CD74FCT244 and CD74FCT244AT devices are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each buffer/driver)

INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	X	Z



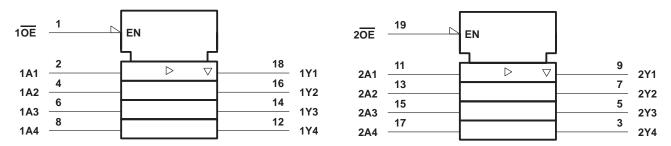
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CD74FCT244, CD74FCT244AT **BICMOS OCTAL BUFFERS/LINE DRIVERS** WITH 3-STATE OUTPUTS

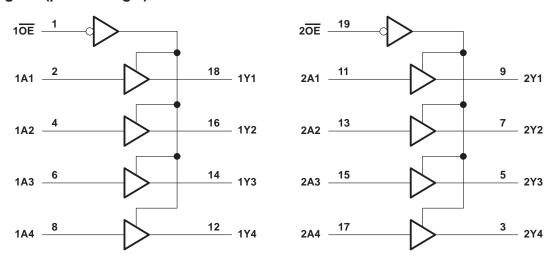
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

DC supply voltage range, V _{CC}		0.5 V to 6 V
DC input clamp current, I_{IK} ($V_I < -0.5 \text{ V}$)		–20 mA
DC output clamp current, I_{OK} ($V_O < -0.5 \text{ V}$)		–50 mA
DC output sink current per output pin, IOL		
DC output source current per output pin, IOH .		
Continuous current through V _{CC} , I _{CC}		
Continuous current through GND		
Package thermal impedance, θ_{JA} (see Note 1):		
5 1 7 0/1 V	M package	
	SM package	
Storage temperature range, T _{sto}	. •	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 2)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.75	5.25	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
٧ _I	Input voltage	0	VCC	V
Vo	Output voltage	0	VCC	V
IOH	High-level output current		-15	mA
loL	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate (slew rate)	0	10	ns/V
TA	Operating free-air temperature	0	70	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	T _A = 25°C		MIN	MAX	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	MAX	IVIIIN	WIIN WAX	UNIT
V _{IK}	$I_{I} = -18 \text{ mA}$	4.75 V		-1.2		-1.2	V
Vон	I _{OH} = -15 mA	4.75 V	2.4		2.4		V
VOL	$I_{OL} = 64 \text{ mA}$	4.75 V		0.55		0.55	V
lį	$V_I = V_{CC}$ or GND	5.25 V		±0.1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.25 V		±0.5		±10	μΑ
los†	$V_I = V_{CC}$ or GND, $V_O = 0$	5.25 V	-60		-60		mA
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.25 V		8		80	μΑ
Δl _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.25 V		1.6		1.6	mA
Ci	V _I = V _{CC} or GND			10		10	pF
Co	$V_O = V_{CC}$ or GND			15		15	pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 100 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.25 V (unless otherwise noted) (see Figure 1)

PARAMETER			CD74FCT244			CD74FCT244AT			
	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C	MIN	MAX	T _A = 25°C	MIN	MAX	UNIT
			TYP			TYP			
^t pd	А	Υ	4.5	1.5	6.5	3.8	1.5	5.3	ns
^t en	ŌĒ	Υ	6	1.5	8	4.8	1.5	6.5	ns
^t dis	ŌĒ	Y	5	1.5	7	4.5	1.5	5.8	ns

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V _{OL}		1		V
VOH(V)	Quiet output, minimum dynamic VOH		0.5		V
VIH(D)	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V



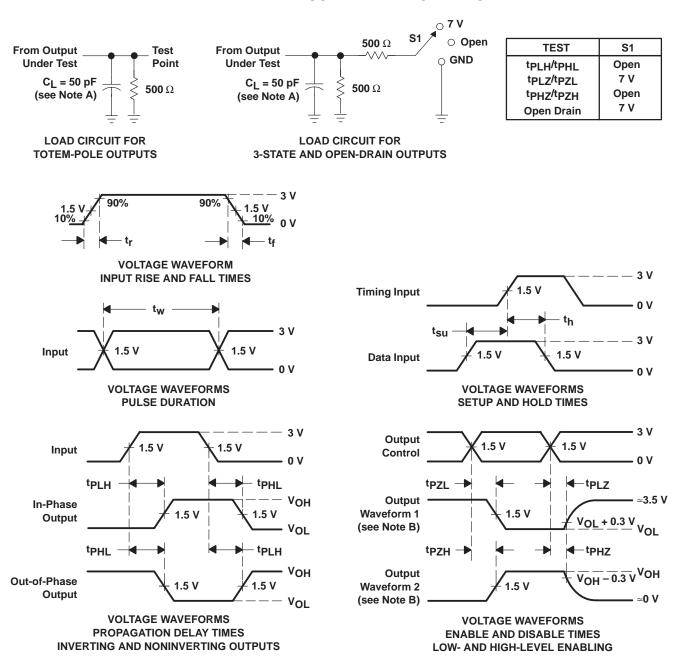
 $[\]ddagger$ This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

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operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load, f = 1 MHz	35	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, t_f and $t_f = 2.5$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PHL} and t_{PLH} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms



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